

## Electronic Patent Application Fee Transmittal

<b>Application Number:</b>	10717122
<b>Filing Date:</b>	19-Nov-2003
<b>Title of Invention:</b>	Dielectric barrier layer for a copper metallization layer having a varying silicon concentration along its thickness
<b>First Named Inventor/Applicant Name:</b>	Larry Zhao
<b>Filer:</b>	J. Mike Amerson/Mary Paul
<b>Attorney Docket Number:</b>	2000.106900

Filed as Large Entity

### Utility Filing Fees

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
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**Basic Filing:**

**Pages:**

**Claims:**

**Miscellaneous-Filing:**

**Petition:**

**Patent-Appeals-and-Interference:**

Post-Allowance-and-Post-Issuance:

**Extension-of-Time:**

Extension - 3 months with \$0 paid	1253	1	1020	1020
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Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Miscellaneous:</b>				
<b>Total in USD (\$)</b>				<b>1020</b>